



ASE Selected by Medtronic to Package its Sophisticated Integrated Circuits for Medical Devices

Full turnkey for IC packaging solution enables Medtronic to deliver complex life-enhancing devices while realizing faster time to market

Santa Clara, California, 29th August, 2006 – Advanced Semiconductor Engineering Incorporated (ASE, TAIEX: 2311, NYSE: ASX), the world's largest semiconductor packaging and test company, announced today that it has been selected by Medtronic, Inc. (NYSE: MDT) as its IC packaging and test services partner for a range of devices used in medical implantable pacemaker and defibrillator devices. ASE was chosen for its strength in technology, and its capability to provide Medtronic with full turnkey service.

While ASE has traditionally focused on solutions for applications within the 3 C's sector, the company's portfolio is expanding to include IC packaging and test solutions for highly complex medical applications. As the world's leading provider of pacemaker and defibrillator devices, Medtronic depends upon reliable, quality, and highly-functional semiconductor chips to power its intricate devices.

By applying advanced technologies to integrate more features, functions, and performance, ASE delivers packaging solutions, which, combined with the integration of surface mount, wire bond, and flip chip interconnect technology, enable superior performance and functionality at the device level. ASE's advanced wafer bumping technologies enable the fundamental interconnection between die and substrate, critical in reducing signal propagation delay, providing improved bandwidth, and relieving the constraints of power and ground distribution.

"Medtronic is making significant breakthroughs in the medical field and we are pleased that our technology and service is contributing to such a sophisticated line of life support products," said Rich Rice, senior vice president of sales, North America, ASE (U.S.) Inc. "Because of our extensive experience in providing turnkey solutions, we are able to share our expertise with Medtronic and assist them in getting their products to market faster. Additionally, ASE is expanding the company's portfolio to include IC packaging solutions for highly complex medical applications."

About ASE Group

The ASE Group is the world's largest provider of independent semiconductor manufacturing services in assembly and test. As a global leader geared towards meeting the

industry's ever growing needs for faster, smaller and higher performance chips, the Group develops and offers a wide portfolio of technology and solutions including IC test program design, front-end engineering test, wafer probe, wafer bump, substrate design and supply, wafer level package, flip chip, system-in-package, final test and electronic manufacturing services through Universal Scientific Industrial Co Ltd, a member of the ASE Group. The Group generated sales revenues of \$2.6 billion in 2005 and employs over 32,000 people worldwide. For more information about the ASE Group, visit www.aseglobal.com.

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